

SOT1397-4

wafer level chip-scale package, 20 bumps

26 April 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP20
Package type industry code	WLCSP20
Package style descriptive code	WLCSP (wafer level chip-size package)
Package style suffix code	NA (not applicable)
Mounting method type	S (surface mount)
Issue date	26-4-2016

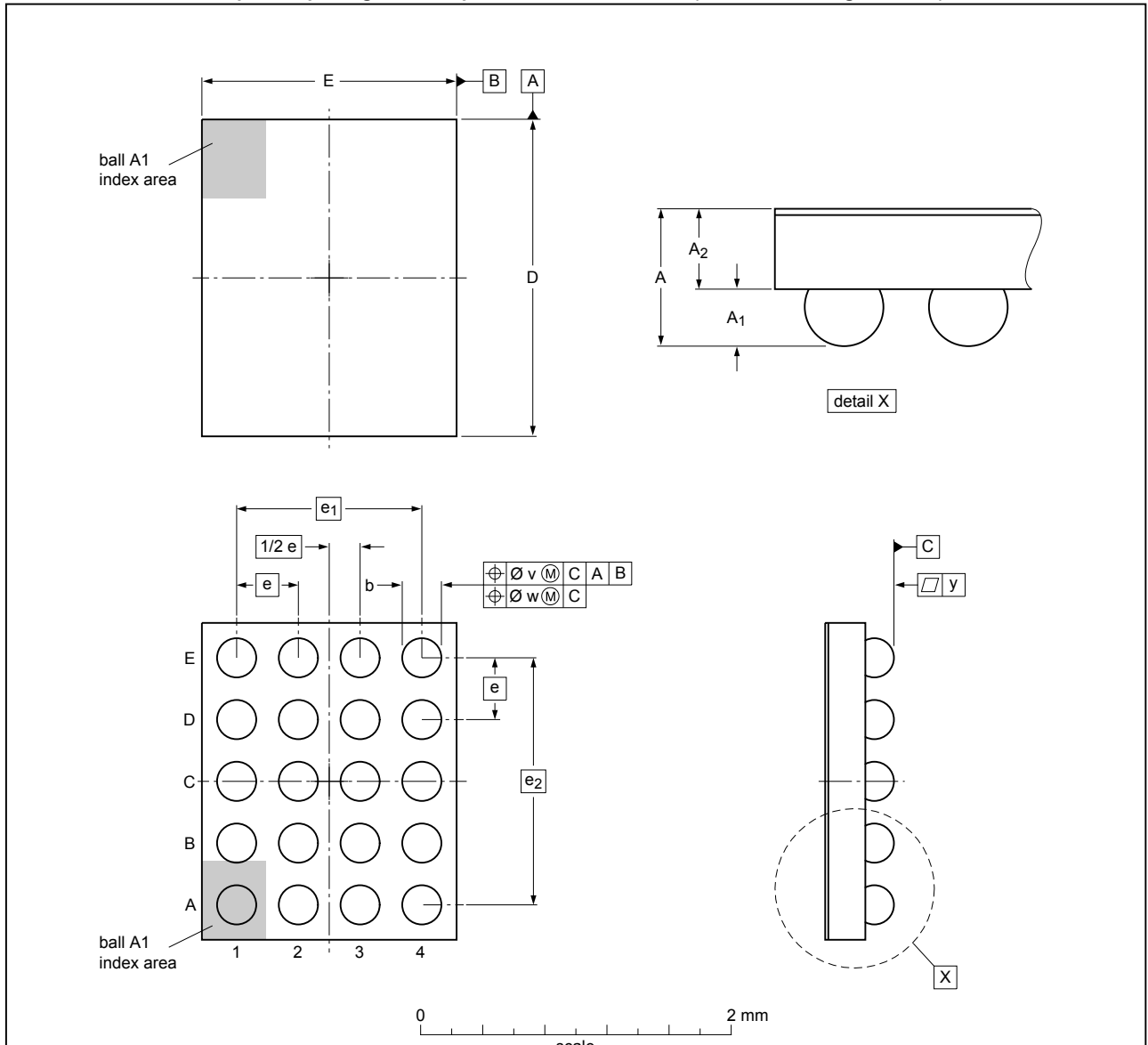
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.01	-	2.04	2.07	mm
E	package width	1.61	-	1.64	1.67	mm
A	seated height	0.41	-	0.45	0.49	mm
A ₂	package height	0.225	-	0.25	0.275	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	20	-	



2. Package outline

WLCSP20: wafer level chip-scale package; 20 bumps; 2.04 x 1.64 x 0.45 mm (Backside coating included) SOT1397-4



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y
max	0.49	0.23	0.275	0.29	2.07	1.67						
mm nom	0.45	0.20	0.250	0.26	2.04	1.64	0.4	1.2	1.6	0.15	0.05	0.05
min	0.41	0.17	0.225	0.23	2.01	1.61						

Note: Backside coating 25 µm

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
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Fig. 1. Package outline WLCSP20 (SOT1397-4)

3. Legal information

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